



Product Change Notification / JAON-16UWYU638

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**Date:**

27-Nov-2015

**Product Category:**

Power MOSFET Drivers

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 1747 Final Notice: Qualification of non-conductive die attach epoxy 8900NC for selected products available in 8L SOIC package at MTAI assembly site.

**Notification Text:**

**PCN Status:** Final notification

**Microchip Parts Affected:**Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**Qualification of non-conductive die attach epoxy 8900NC for selected products available in 8L SOIC package at MTAI assembly site.

**Pre Change:** Using conductive die attach epoxy 8390A.

**Post Change:**Using non-conductive die attach epoxy 8900NC.

**Pre and Post Change Summary:**

	<b>Pre Change</b>	<b>Post Change</b>
<b>Assembly Site</b>	MTAI assembly site	MTAI assembly site
<b>Wire material</b>	Au wire	Au wire
<b>Die attach material</b>	8390A (conductive die	8900NC (non-conductive die

	attach epoxy)	attach epoxy)
<b>Molding compound material</b>	SG-8300GM or G600IMP10 or G600V	G600IMP10 or G600V
<b>Lead frame material</b>	C194	C194

**Impacts to Data Sheet:** None

**Reason for Change:**To improve manufacturability by qualifying non-conductive die attach epoxy 8900NC at MTAI assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**December 27, 2015 (date code: 1552)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Summary Table:**

	September 2015					October 2015				November 2015				December 2015				
WW	36	37	38	39	40	41	42	43	44	45	46	47	48	49	50	51	52	53
Initial PCN Issue Date				X														
Qual Report Availability								X										
Final PCN Issue Date													X					
Implementation Date																	X	

**Markings to Distinguish Revised from Unrevised Devices:** Traceability code

**Revision History:****September 21, 2015:** Issued initial notification.**November 27, 2015:** Issued final notification. Attached the qualification report. Revised the estimated first ship date from November 30, 2015 to December 27, 2015.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

- [PCN\\_JAON-16UWYU638\\_Qual\\_Report.pdf](#)
- [PCN\\_JAON-16UWYU638\\_Affected\\_CPN.pdf](#)
- [PCN\\_JAON-16UWYU638\\_Affected\\_CPN.xls](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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